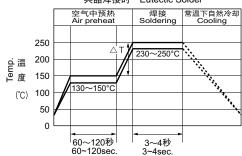
## Part number CSA<sub>20</sub> CSA30 CSA70 CDA70 TH03 TX03 **TN05** TC05 **TH05** TD05 **TX05** TZ05 **TN11 TH11** TD11 **TN10** TC10 **TN20** TC20 TH20 **MN18** MH18 **GA13 GA20 %**1 GH13 GH20

#### 焊接条件 Soldering conditions

# 推荐温度曲线 Recommended Temperature Profile

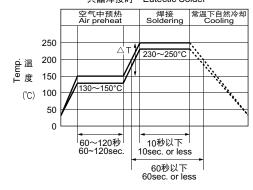
流体焊接 Flow soldering conditions





- 1) 保持时间为元件表面温度达到上述温度后起算的时间。
- 2) △T应在100℃以内。
- 3) 焊接后切勿迅速冷却, 而应缓慢冷却。
- 1) Time shown in the above figures is measured from the point when chip surface reaches temperature.
- 2) Temperature difference in high temperature part should be within 100°C
- 3) After soldering, do not force cool, allow the parts to cool gradually.

回流焊接 Reflow soldering conditions 共晶焊接时 Eutectic Solder

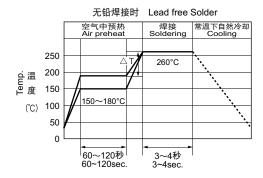


- 1) 保持时间为元件表面温度达到上述温度后起算的时间。
- 2) △T应在100℃以内。
- 3) 焊接后切勿迅速冷却, 而应缓慢冷却。
- Time shown in the above figures is measured from the point when chip surface reaches temperature.
- Temperature difference in high temperature part should be within 100°C.
- 3) After soldering, do not force cool, allow the parts to cool gradually.

※1 仅可进行回流焊接

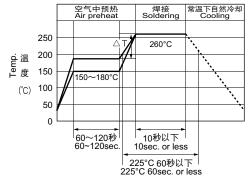
※2 仅为镀锡品或仅适用于流动焊接。

其它产品请在规格书所记载的条件下使用。



- 1) 保持时间为元件表面温度达到上述温度后起算的时间。
- 2) ∧T应在110℃以内。
- 3) 焊接后切勿迅速冷却, 而应缓慢冷却。
- Time shown in the above figures is measured from the point when chip surface reaches temperature.
- 2) Temperature difference in high temperature part should be within 110°C
- 3) After soldering, do not force cool, allow the parts to cool gradually.

## 无铅焊接时 Lead free Solder



- 1) 保持时间为元件表面温度达到上述温度后起算的时间。
- 2) △T应在110℃以内。
- 3) 焊接后切勿迅速冷却, 而应缓慢冷却。
- 1) Time shown in the above figures is measured from the point when chip surface reaches temperature.
- Temperature difference in high temperature part should be within 110°C.
- 3) After soldering, do not force cool, allow the parts to cool gradually.
- ※1 Reflow only
- ※2 Tin plated only, and flow only.

Soldering method of the other products refer to the individual specification.

### 【焊接时的一般注意事项】

- ●若焊接温度过高、焊接时间过长,端子电极处可能会发生浸析,从而导致粘着力下降或性能劣化。
- ●焊接时请参照上述温度曲线进行。 但超过200℃的温度应控制在50秒以内。
- ●焊剂应使用低活性(CI含有率在0.2wt%以下)的产品。如果焊剂为水溶性、且清洗不充分的话,可能会损伤元件下部的绝缘,应予以注意。

#### 【清洗】

用超声波进行清洗时,输出过大会引起主板共振,振动可能会造成主板破裂或端 子电极粘着力下降。故此,推荐按以下条件进行清洗。

> 频 率: 40kHz以下输 出: 20W/ ℓ 清洗时间: 5分钟以内

### General attention to soldering

- High soldering temperatures and long soldering times can cause leaching
  of the termination, decrease in adherence strength, and the change of
  characteristic may occur.
- For soldering, please refer to the soldering curves above.
   However, please keep exposure to temperatures exceeding 200°C to under 50 seconds.
- Please use a mild flux(containing less than 0.2wt% Cl). Also, if the flux is water soluble, be sure to wash thoroughly to remove any residue from the underside of components, that could affect resistance.

## Cleaning

When using ultrasonic cleaning, the board may resonate if the output power is too high. Since this vibration can cause cracking or a decrease in the adherence of the termination, we recommend that you use the conditions below.

Frequency: 40kHz max.
Output power: 20W/liter
Cleaning time:5minutes max.